

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20160629002 Qualification of MAINEFAB for select ABCD150 devices Change Notification / Sample Request

Date: 7/5/2016

To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN www admin team@list.ti.com).

PCN Team SC Business Services

20160629002 Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM25118MH/NOPB	null
LMZ14201HTZX/NOPB	null
LMR62014XMFE/NOPB	null
LMZ14201HTZ/NOPB	null
LM25118MHE/NOPB	null
LM25118MHX/NOPB	null
LMR62014XMF/NOPB	null
LMZ14202HTZ/NOPB	null
LMZ14203HTZ/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number: 201				0160	62	9002			P	CN Date:	7/5/2016
Titl	Title: Qualification of MAINEFAB for select ABCD150 devices										
Customer Contact:			PCN	I M	<u>lanager</u>		Dept:		Quality Ser	vices	
Proposed 1 st Ship Date: 10,		10/	5/2	2016	Estimate Availabil	d Sample ity:			led at sample		
Change Type:											
Assembly Site				Assembly	y Process	Process Assembly Materials		Materials			
	Desigr	1			Electrical Specification		ion		Mechanical Specification		
	Test S	ite				Packing/	ng/Shipping/Labeling		SS		
	Wafer	Bump Site		Wafer Bump Material			al		Wafer Bun	np Process	
\boxtimes	Wafer	Fab Site				S		Wafer Fab	Process		
	Part number change										
	PCN Details										

Description of Change:

Texas Instruments is pleased to announce the qualification of its MAINEFAB fabrication facility as a wafer Fab source for the devices listed in "Product Affected" section of this document.

	Current			New	
Chip Sites	Process	Wafer Diameter	Chip Site	Process	Wafer Diameter
GFAB6	ABCD150	150mm	MAINEFAB	ABCD150	200mm
GFAB8	ABCD150	200mm	MAINEFAB	ABCD150	200mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Sites	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
GFAB6	GF6	GBR	Greenock
GFAB8	GF8	GBR	Greenock

New

MAINEFAB	CUA	USA	South Portland
Chip Site	(20L)	Code (21L)	Chip Site City
	Chip Site Origin Code	Chip Site Country	

Sample product shipping label (not actual product label)





3959047MLA TKY(1T) 7523483S12 (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (23L) ACO. MYS

Product Affected:			
EMB1420MME/NOPB	LM5025DMTCX/NOPB	LMZ14201HTZX/NOPB	SM74202MME-2/NOPB
EMB1487MM/NOPB	LMR24210TL/NOPB	LMZ14202HTZ/NOPB	SM74202MMX-2/NOPB
EMB1487MME/NOPB	LMR24210TLX/NOPB	LMZ14202HTZE/NOPB	SM74203MM/NOPB
EMB1487MMX/NOPB	LMR24220TL/NOPB	LMZ14202HTZX/NOPB	SM74203MME/NOPB
LM25118MH/NOPB	LMR24220TLX/NOPB	LMZ14203HTZ/NOPB	SM74203MMX/NOPB
LM25118MHE/NOPB	LMR61428XMM/NOPB	LMZ14203HTZE/NOPB	TPS92690PWP/NOPB
LM25118MHX/NOPB	LMR61428XMMX/NOPB	LMZ14203HTZX/NOPB	TPS92690PWPR/NOPB
LM2687-W	LMR62014XMF/NOPB	SM72482MA-4/NOPB	WPMDH1102401JT/NOPB
LM3409N/NOPB	LMR62014XMFE/NOPB	SM72482MAE-4/NOPB	WPMDH1152401JT/NOPB
LM3478MMX/S5000085	LMR62014XMFX/NOPB	SM72482MAX-4/NOPB	WPMDH1200601JT/NOPB
LM5007MM/S7003020	LMZ14201HTZ/NOPB	SM74202MM-2/NOPB	WPMDH1302401JT/NOPB
LM5025DMTC/NOPB	LMZ14201HTZE/NOPB		

Automotive Qualification Report ABCD150 Fab Process Qualification in Maine Fab Approve Date: 7-December-2010

Product Attributes

Attributes	Qual Device: LP38691QSD-ADJ	QBS Device #1: LP3907QSQ-JXIP	QBS Device #2: LMH6722QSD	QBS Device #3: DS25CP102QSQ	QBS Device #4: DS99R421QSQ
Wafer Fab Site:	Maine Fab	Maine Fab	Maine Fab	Maine Fab	Maine Fab
Wafer Diameter:	200mm	200mm	200mm	200mm	200mm
Fab Process Description:	ABCD150	ABCD150	ABCD150	ABCD150	ABCD150

⁻ QBS: Qual by Similarity - MSL Level 1 @260

Qualification ResultsData Displayed as: Number of lots/Total sample size / Total failed

Test/Methods	Conditions	Measurement	ATE	Qual Device: LP38691QSD- ADJ	QBS Device #1: LP3907QSQ-JXIP		QBS Device #3: DS25CP102QSQ	QBS Device #4: DS99R421QSQ
ELFR	42500	405	25°C	3/2397/0	-	-	-	-
JESD22-A108	125°C	48hrs	125°C	3/2397/0	-	-	-	-
			25°C	-	1/77/0	2/154/0	2/154/0	1/77/0
THBT	85°C, 85%,	1000hrs	85°C	-	-	-	2/154/0	-
JESD22-A101	33.3psia	TOOONIS	105°C	-	-	-	-	1/77/0
			125°C	-	1/77/0	2/154/0	-	-
			25°C	3/231/0	-	-	-	-
OPL JESD22-A108	125°C	1000hrs	150°C	3/231/0	-	-	-	-
020022 A100			-40°C	3/231/0	-	-	-	-
			25°C	-	1/45/0	1/90/0	1/77/0	1/77/0
HTSL	45000	40001	85°C	-	-	-	1/77/0	-
JESD22-A103	150°C	1000hrs	105°C	-	-	-	-	1/77/0
			125°C	-	1/45/0	1/90/0	-	-
			25°C	-	1/77/0*	-	2/154/0*	1/77/0*
TMCL	-65°C to 150°C	500	85°C	-	-	-	2/154/0*	-
JESD22-A104	-05°C to 150°C	500cyc	105°C	-	-	-	-	1/77/0*
			125°C	-	1/77/0*	-	-	-
ACLV JESD22-A102	121°C, 100%, 14.7PSI	96hrs	25°C	-	-	3/231/0	1/77/0	1/77/0
ESDH	1.5 kOhms, 100pF, Room	2000V	25°C	1/3/0	-	-	-	-
LSDIT	Temp	2000	125°C	1/3/0	-	-	-	-
ESDM	0 Ohm, 200pF,	200V	25°C	1/3/0	-	-	-	-
ESDIM	Room Temp	2000	125°C	1/3/0	-	-	-	-
	Peak current pulse based on		25°C	1/3/0	-	-	-	-
ESDC	package parasitic impedance	750V	125°C	1/3/0	-	-	-	-
	Current and Over Voltage test at	25°C	25°C	1/6/0	-	-	-	-
LUPS	Max Ambient Operating Temp	125°C	150°C	1/6/0	-	-	-	-
GTLK	155°C	+/-400V	25°C	1/3/0	-	-	-	-

Preconditioning was performed for ACLV, TMCL, THBT as per JESD22-A113
 Passed wirebond pull test after TMCL 500cyc

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/ Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

Qualification Report ABCD150XV1 Fab Process Qualification in Maine Fab Approve Date: 13-June-2007

Product Attributes

Attributes	Qual Device: LM5010MH/NOPB
Wafer Fab Site:	Maine Fab
Wafer Diameter:	200mm
Fab Process Description:	ABCD150
Assembly Location:	TIEMA

⁻ MSL Level 1 @260

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: LP38691QSD-ADJ
ACLV	Autoclave 121°C	96 hours	1/50/0
THBT	Temperature & Humidity	168 hours	1/77/0
OPL	Operational Life 125°C	1000hrs	3/231/0
HTSL	High Temp Storage Life (150°C)	1000hrs	1/76/0
TMCL	Temp Cycle (-65°C / +150°C)	500cyc	1/77/0
ESDH	ESD HBM	+/- 1000V	3/9/0
ESDC	ESD CDM	+/- 250V	3/9/0
LU	Latch-Up	(per JESD78)	3/18/0

⁻ Preconditioning Level 1 was performed for ACLV, TMCL, THBT as per JESD22-A113

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com